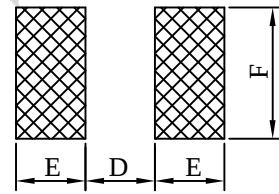
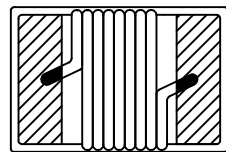
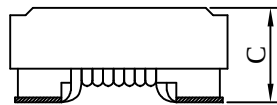
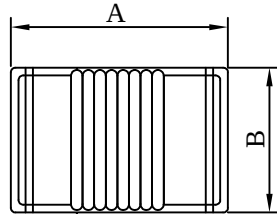


SPECIFICATION FOR APPROVAL

REF. :

PROD. NAME	Wound Chip Inductor	ABC'S DWG NO.		ESW1210□□□□L□-□□□	
		REV.	20240812	PAGE	1

I . Configuration and dimensions :



(PCB Pattern)

Unit : mm

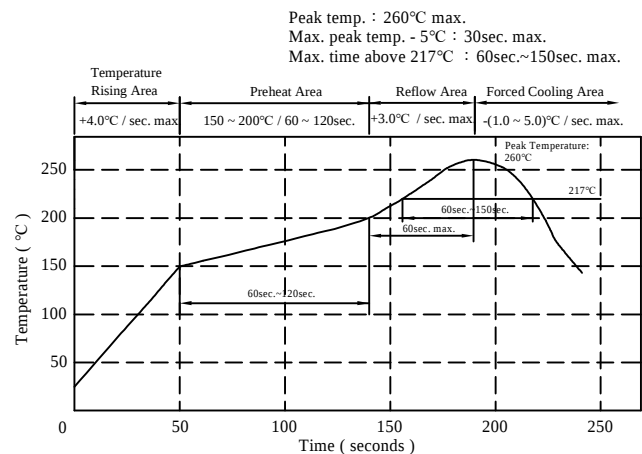
A	B	C	D	E	F
3.50 max.	2.90 max.	2.25 max.	1.78 typ.	1.02 typ.	2.54 typ.

II . Description :

- a . Body : Ceramic
- b . Enamelled copper wire : H class
- c . Product weight : 40 mg (ref.)
- d . Moisture sensitivity Level 2
- e . Products comply with RoHS' requirements
- f . Halogen free

III . General specification :

- a . Operating temp. : -40°C----+85°C
(Temp. rise included)
- b . Resistance to solder heat : 260°C.10 sec.



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SPECIFICATION FOR APPROVAL

REF. :

PROD. NAME	Wound Chip Inductor	ABC'S DWG NO.		ESW1210□□□□L□-□□□		
		REV.	20240812	PAGE	2	

IV . Electrical characteristics :

DWG No.	Inductance (nH)	Tolerance	Q min.	Test Freq. (MHz)		SRF (MHz) min.	RDC (Ω) max.	Irms (mA) typ.
				L	Q			
ESW121010N□L□-□□□	10.0	J,K,M	40	100	300	4000	0.08	1000
ESW121012N□L□-□□□	12.0	J,K,M	40	100	300	3200	0.08	1000
ESW121015N□L□-□□□	15.0	J,K,M	40	100	300	3200	0.20	1000
ESW121018N□L□-□□□	18.0	J,K,M	50	100	300	2800	0.10	1000
ESW121022N□L□-□□□	22.0	J,K,M	50	100	300	2200	0.10	1000
ESW121027N□L□-□□□	27.0	J,K,M	50	100	300	1800	0.11	1000
ESW121033N□L□-□□□	33.0	J,K,M	55	100	300	1800	0.11	1000
ESW121039N□L□-□□□	39.0	J,K,M	55	100	300	1500	0.12	1000
ESW121043N□L□-□□□	43.0	J,K,M	55	100	300	1500	0.12	1000
ESW121047N□L□-□□□	47.0	J,K,M	55	100	300	1500	0.13	1000
ESW121056N□L□-□□□	56.0	J,K,M	55	100	300	1450	0.14	1000
ESW121068N□L□-□□□	68.0	J,K,M	55	100	300	1200	0.15	900
ESW121082N□L□-□□□	82.0	J,K,M	55	100	300	1000	0.20	900
ESW121091N□L□-□□□	91.0	J,K,M	60	100	300	1100	0.20	1000
ESW1210R10□L□-□□□	100.0	G,J,K,M	55	100	300	900	0.20	850
ESW1210R12□L□-□□□	120.0	G,J,K,M	60	100	300	800	0.25	800
ESW1210R15□L□-□□□	150.0	G,J,K,M	60	100	300	700	0.30	750
ESW1210R18□L□-□□□	180.0	G,J,K,M	60	50	300	650	0.30	700
ESW1210R22□L□-□□□	220.0	G,J,K,M	60	50	300	650	0.40	770
ESW1210R24□L□-□□□	240.0	G,J,K,M	40	50	300	580	0.40	630
ESW1210R27□L□-□□□	270.0	G,J,K,M	40	50	300	580	0.40	630
ESW1210R33□L□-□□□	330.0	G,J,K,M	45	50	150	580	0.58	590
ESW1210R36□L□-□□□	360.0	G,J,K,M	45	50	150	510	0.58	530
ESW1210R39□L□-□□□	390.0	G,J,K,M	45	50	150	510	0.58	530
ESW1210R47□L□-□□□	470.0	G,J,K,M	45	50	150	480	1.00	490
ESW1210R56□L□-□□□	560.0	G,J,K,M	45	25	150	420	1.10	460
ESW1210R68□L□-□□□	680.0	G,J,K,M	45	25	150	400	1.20	430
ESW1210R82□L□-□□□	820.0	G,J,K,M	45	25	150	370	2.00	400
ESW12101R0□L□-□□□	1000.0	G,J,K,M	45	25	150	340	1.85	320
ESW12101R2□L□-□□□	1200.0	G,J,K,M	45	25	150	220	2.30	300
ESW12101R5□L□-□□□	1500.0	G,J,K,M	20	7.9	50	160	2.70	310
ESW12101R8□L□-□□□	1800.0	G,J,K,M	30	7.9	50	160	3.50	310
ESW12102R2□L□-□□□	2200.0	G,J,K,M	25	7.9	50	130	2.41	310
ESW12102R7□L□-□□□	2700.0	G,J,K,M	25	7.9	50	110	3.50	300
ESW12103R0□L□-□□□	3000.0	G,J,K,M	20	7.9	25	110	3.50	300
ESW12103R3□L□-□□□	3300.0	G,J,K,M	20	7.9	25	60	3.60	290
ESW12103R9□L□-□□□	3900.0	G,J,K,M	20	7.9	25	60	4.00	290
ESW12104R7□L□-□□□	4700.0	G,J,K,M	20	7.9	25	60	5.00	280
ESW12105R2□L□-□□□	5200.0	G,J,K,M	15	7.9	25	50	6.00	250

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SPECIFICATION FOR APPROVAL

REF. :

PROD. NAME	Wound Chip Inductor	ABC'S DWG NO.		ESW1210□□□□L□-□□□		
		REV.	20240715	PAGE	2-1	

DWG No.	Inductance (nH)	Tolerance	Q min.	Test Freq. (MHz)		SRF (MHz) min.	RDC (Ω) max.	Irms (mA) typ.
				L	Q			
ESW12105R6□L□-□□□	5600.0	G,J,K,M	15	7.9	25	50	6.00	250
ESW12106R8□L□-□□□	6800.0	G,J,K,M	15	7.9	7.9	40	9.00	230
ESW12107R5□L□-□□□	7500.0	G,J,K,M	20	7.9	7.9	50	9.50	170
ESW12108R2□L□-□□□	8200.0	G,J,K,M	20	7.9	7.9	50	9.50	170
ESW12108R6□L□-□□□	8600.0	G,J,K,M	15	7.9	7.9	40	9.00	200
ESW1210100□L□-□□□	10000.0	G,J,K,M	15	7.9	7.9	30	10.00	150

- 1). Electrical specifications at 25°C
- 2). Irms base on temp. rise 40°C typ.
- 3). Tolerance : S(±0.3) 、 G(±2%) 、 J(±5%) 、 K(±10%) 、 M(±20%)

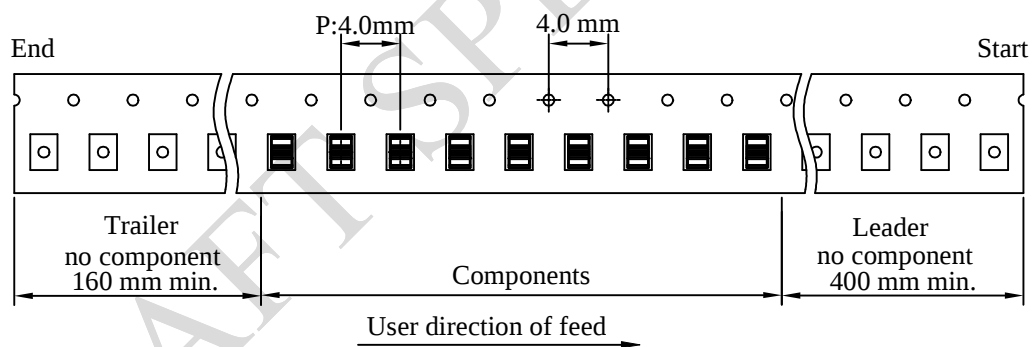
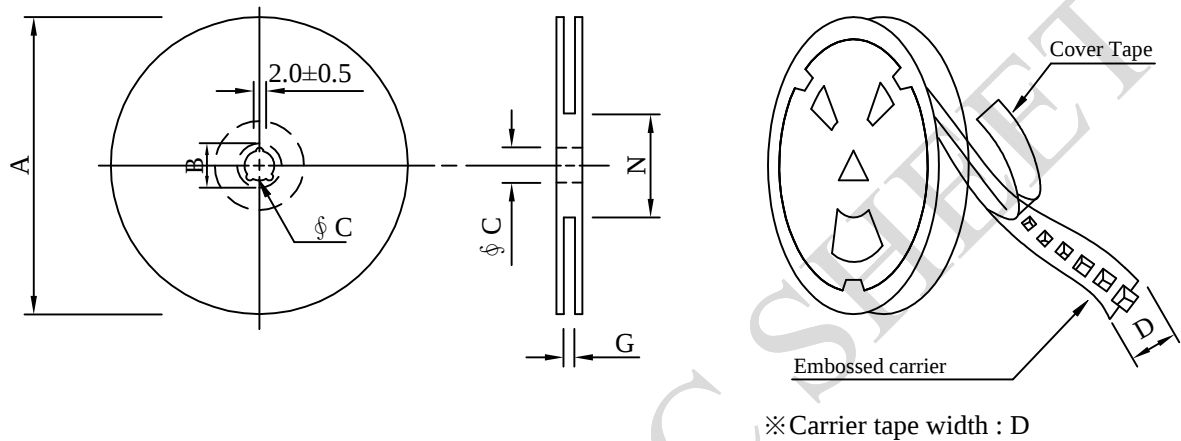
SPECIFICATION FOR APPROVAL

REF. :

PROD. NAME	Wound Chip Inductor	ABC'S DWG NO.		ESW1210□□□□L□-□□□		
		REV.	20240812	PAGE	3	

V . Packaging information :

(1) Configuration



(2) Dimensions

Unit:mm

Style	A	B	C	D	G	N	T
07 - 08	178	21	13	8	8.4^{+0}	60^{-0}	12.4

(3) Q'TY & G.W. Per package

Code	Inner : Reel			Outer : Carton		
	Q'TY (pcs)	G.W. (g)	Style	Q'TY (pcs)	G.W. (kg)	Size (cm)
B	2,000	210	07 - 08	100,000	11.8	39.5 x 39.5 x 23

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REF. :

PROD. NAME	Wound Chip Inductor	ABC'S DWG NO.		ESW1210□□□□L□-□□□		
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VI . Drawing number expression :

E	S	W	1	2	1	0	□	□	□	□	L	□	—	□	□	□
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Reference code

Appendix code 2 : Package

Appendix code 1 : Classification

Tolerance code

Electrical code

Dimension code

Type code

Appendix code 1 : Product Classification

Appendix code 2 : Package Information

Code	Inner package	Cover tape	Carrier tape	Bag	Package Q'TY	Remark
B	T /R (Reel package)	NA	NA	NA	2,000 pcs	

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SPECIFICATION FOR APPROVAL

REF. :

PROD. NAME	Wound Chip Inductor	ABC'S DWG NO.	ESW1210□□□□L□-□□□		
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VII . Safety notes :

1. Products do not be used in related applications that directly affect the personal safety system or cause significant impacts and losses on society. If you apply to these applications, please be sure to contact us at first to confirm.
產品不可使用於直接影響人身安全系統或對社會會造成重大影響與損失之相關用途，若您應用於此，請務必優先與我們聯繫確認。
2. The storage period is less than 12 months. Ensure to follow the storage conditions (Temperature: 5 to 30°C, Humidity: 10 to 60% RH or less). If the storage time is exceeded the limit, the electrodes might be deteriorate of terminal soldering.
儲存期不超過12個月，務必遵守儲存條件（溫度：5至30°C，濕度：10至60%RH以下）。如果超過了儲存時間，端子電極可能會氧化而影響焊接。
3. Do not use or store in locations where there are conditions such as gas corrosion (salt, acid, alkali, etc.).
不要在有氣體腐蝕等條件的地方使用或存放（鹽，酸，鹼等）。
4. Soldering corrections after mounting should be within the range of the conditions determined in the specifications. If overheated, a short circuit, performance deterioration, or lifespan shortening may occur.
安裝時的焊接條件應在規格範圍內。如果超過要求，可能會發生短路，性能下降或壽命縮短。
5. When using, it should try to avoid excessive mechanical impact on the product, such as collision / drop ... and other reasons.
使用時，應盡量避免產品受到過度機械衝擊，如碰撞/掉落...等原因。
6. When embedding a printed circuit board where a chip is mounted to a set, be sure that residual stress is not given to the chip due to the overall distortion of the printed circuit board and partial distortion such as at screw tightening portions.
將已安裝新片的電路板組裝到裝置時，請注意應盡量避免電路板受到組裝變形...等，導致產品受到應力。
7. Self heating (temperature increase) occurs when the power is turned ON, so the tolerance should be sufficient for the set thermal design.
產品會因通電而自我發熱(溫度上升)，因此在熱影響設計方面，需保留適當公差。
8. Do not expose the products to magnets or magnetic fields.
請勿將產品暴露於磁鐵或是磁場中。
9. If you would like to use this products to performance and/or quality require a more stringent level of safety or reliability, or whose failure, malfunction or trouble could cause serious damage to society, person or property, or if you have special requirements exceeding the range or conditions set forth in the each catalog, please contact us.
如果您希望將此產品用於性能和/或質量要求更嚴格的安全性或可靠性，或其失敗、故障或麻煩可能對社會、個人或財產造成嚴重損害，或者您有特殊情況要求超出目錄中規定的範圍或條件，請與我們聯繫。